

Shan 2nd & 3rd

AN 127:22028 HCA
TI **Copper** alloys for electronic apparatus and their manufacture
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SO Jpn. Kokai Tokkyo Koho, 9 pp.
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AB The title **Cu** alloys contain Cr 0.1-0.4, Sn 0.05-2, Zn 0.05-2, **Pb** and/or Ca total 0.005-0.2, P < 0.01, S < 0.005 and O2 < 0.005%; size of crystd. or pptd. substances < 3 .mu.m, and grain size < 5 .mu.m. Optionally, the **Cu** alloys may also contain Zr 0.01-0.2%. The **Cu** alloys for electronic app. are manufd. by **casting** the above stated **Cu** alloys at cooling speed .gtoreq. 5.degree./s, hot working at 850-1000.degree., cooling at cooling speed .gtoreq. 10.degree./s, cold working at draft .gtoreq. 80%, **heat** treating at 400-500.degree. for 10 min to 24 h, cold working at draft .ltoreq.

50%, and final **heat** treating at 300-600.degree. for 10 min to 12 h in order. The **Cu** alloys have good strength, elec. cond., solderability, and punchability.